

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Longxing Shi</td> <td>02/25/2013</td> </tr> <tr> <td>Qinsong Qian</td> <td>02/25/2013</td> </tr> <tr> <td>Changlong Huo</td> <td>02/25/2013</td> </tr> <tr> <td>Weifeng Sun</td> <td>02/25/2013</td> </tr> <tr> <td>Shengli Lu</td> <td>02/25/2013</td> </tr> </tbody> </table>		Name	Execution Date	Longxing Shi	02/25/2013	Qinsong Qian	02/25/2013	Changlong Huo	02/25/2013	Weifeng Sun	02/25/2013	Shengli Lu	02/25/2013
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Longxing Shi	02/25/2013												
Qinsong Qian	02/25/2013												
Changlong Huo	02/25/2013												
Weifeng Sun	02/25/2013												
Shengli Lu	02/25/2013												
RECEIVING PARTY DATA													
Name:	SOUTHEAST UNIVERSITY												
Street Address:	No. 2 Sipailou, Xuanwu												
Internal Address:	Ninjing												
City:	Jiangsu												
State/Country:	CHINA												
Postal Code:	210096												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13819286</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13819286								
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Application Number:	13819286												
CORRESPONDENCE DATA													
Fax Number:	5208827643												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	5208827623												
Email:	jgood@hayes-soloway.com												
Correspondent Name:	Norman P. Soloway												
Address Line 1:	4640 E. Skyline Drive												
Address Line 4:	Tucson, ARIZONA 85718												
ATTORNEY DOCKET NUMBER:	JINGWEI OP13US596P												
NAME OF SUBMITTER:	Norman P. Soloway												

OP \$40.00 13819286

Signature:	/norman p. soloway/
Date:	06/28/2013
Total Attachments: 5 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif source=Assignment#page4.tif source=Assignment#page5.tif	

ASSIGNMENT

I, Longxing Shi of Jiangsu, China having invented certain inventions and improvements in **SILICON ON INSULATOR INTEGRATED HIGH-CURRENT N TYPE COMBINED SEMICONDUCTOR DEVICE** and having executed an application for Letters Patent of the United States of America describing the same and based thereon on the 25 day of February, 2013 (U.S. Patent Application Serial No. 13/819,286 filed February 26, 2013), for good and valuable consideration, the receipt of which is hereby acknowledged from **SOUTHEAST UNIVERSITY**, a Chinese University having its principal place of business at No. 2 Sipailou, Xuanwu, Nanjing, Jiangsu 210096 China (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

And for the same consideration I do agree that I will upon request execute any instrument which the Assignee may desire to carry this Assignment into effect and perfect the title transferred hereby or prosecute the above-mentioned application;

And I do hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America to issue Letters Patent on the said application to the Assignee;

And I do hereby jointly and severally covenant for myself and for my legal representatives that I have granted no right or license to make, use, or sell said invention to anyone except the Assignee, that prior to the execution of this deed my right, title, and interest in and to said inventions or any of them or any part thereof has not been otherwise encumbered by me, and that I have not executed and will not execute any instrument in conflict herewith.

IN WITNESS WHEREOF, I've hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature Longxing Shi Date 20-2-2013
Full name (typed or printed) Longxing Shi

Witness: Shen Xin
Date: 25-2-2013

Witness: Huibin Song
Date: 20-2-2013

ASSIGNMENT

I, Qinsong Qian of Jiangsu, China having invented certain inventions and improvements in **SILICON ON INSULATOR INTEGRATED HIGH-CURRENT N TYPE COMBINED SEMICONDUCTOR DEVICE** and having executed an application for Letters Patent of the United States of America describing the same and based thereon on the 25 day of February, 2013 (U.S. Patent Application Serial No. 13/819,286, filed February 26, 2013), for good and valuable consideration, the receipt of which is hereby acknowledged from **SOUTHEAST UNIVERSITY**, a Chinese University having its principal place of business at No. 2 Sipailou, Xuanwu, Nanjing, Jiangsu 210096 China (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

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IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature Qin Song Qian Date 2-2-2013
Full name (typed or printed) Qinsong Qian

Witness: Shen Xu
Date: 2-2-2013

Witness: Huibin Song
Date: 2-2-2013

ASSIGNMENT

I, Changlong Huo of Jiangsu, China having invented certain inventions and improvements in **SILICON ON INSULATOR INTEGRATED HIGH-CURRENT N TYPE COMBINED SEMICONDUCTOR DEVICE** and having executed an application for Letters Patent of the United States of America describing the same and based thereon on the 25 day of February, 2013 (U.S. Patent Application Serial No. 13/819,286, filed February 26, 2013), for good and valuable consideration, the receipt of which is hereby acknowledged from **SOUTHEAST UNIVERSITY**, a Chinese University having its principal place of business at No. 2 Sipailou, Xuanwu, Nanjing, Jiangsu 210096 China (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or routine application or applications and any patent which may be issued on the said invention in the United States of America;

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IN WITNESS WHEREOF, I've hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature Changlong Huo Date 25-2-2013
Full name (typed or printed) Changlong Huo

Witness: Shen Xin
Date: 25-2-2013

Witness: Huibin Song
Date: 25-2-2013

ASSIGNMENT

I, Weifeng Sun of Jiangsu, China having invented certain inventions and improvements in **SILICON ON INSULATOR INTEGRATED HIGH-CURRENT N TYPE COMBINED SEMICONDUCTOR DEVICE** and having executed an application for Letters Patent of the United States of America describing the same and based thereon on the 25 day of February, 20 13 (U.S. Patent Application Serial No. 13/819,286, filed February 26, 2013), for good and valuable consideration, the receipt of which is hereby acknowledged from **SOUTHEAST UNIVERSITY**, a Chinese University having its principal place of business at No. 2 Sipailou, Xuanwu, Nanjing, Jiangsu 210096 China (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

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IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature Weifeng Sun Date 25-2-2013
Full name (typed or printed) Weifeng Sun

Witness: Shen Xu
Date: 25-2-2013

Witness: Huibin Song
Date: 25-2-2013

ASSIGNMENT

I, Shengli Lu of Jiangsu, China having invented certain inventions and improvements in **SILICON ON INSULATOR INTEGRATED HIGH-CURRENT N TYPE COMBINED SEMICONDUCTOR DEVICE** and having executed an application for Letters Patent of the United States of America describing the same and based thereon on the 25 day of February, 20 13 (U.S. Patent Application Serial No. 13/819,286, filed February 26, 2013), for good and valuable consideration, the receipt of which is hereby acknowledged from **SOUTHEAST UNIVERSITY**, a Chinese University having its principal place of business at No. 2 Sipailou, Xuanwu, Nanjing, Jiangsu 210096 China (hereinafter called the Assignee), do hereby sell, assign and transfer unto the Assignee, its successors, and assigns my entire right, title, and interest, in and to said invention in the United States of America, including all rights, title and interest in the above-mentioned application and any divisional, continuing or reissue application or applications and any patent which may be issued on the said invention in the United States of America;

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IN WITNESS WHEREOF, I/we hereunto set my hand and seal on the day and year hereinafter noted.

Inventor's signature Shengli Lu Date 25-2-2013
Full name (typed or printed) Shengli Lu

Witness: Shen Xia
Date: 25-2-2013

Witness: Huibin Song
Date: 25-2-2013